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IGBT

SGH23N60UFD

Ultra-Fast IGBT

General Description

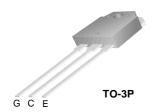
Fairchild's Insulated Gate Bipolar Transistor(IGBT) UFD series provides low conduction and switching losses. UFD series is designed for the applications such as motor control and general inverters where High Speed Switching is required.

Features

- High Speed Switching
- Low Saturation Voltage : $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 12A$
- High Input Impedance
- CO-PAK, IGBT with FRD : t_{rr} = 42ns (typ.)

Application

AC & DC Motor controls, General Purpose Inverters, Robotics, Servo Controls





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Description		SGH23N60UFD	Units	
V _{CES}	Collector-Emitter Voltage		600	V	
V _{GES}	Gate-Emitter Voltage		± 20	V	
	Collector Current	@ T _C = 25°C	23	А	
IC	Collector Current	@ T _C = 100°C	12	А	
I _{CM (1)}	Pulsed Collector Current	-	92	Α	
I _F	Diode Continuous Forward Current	@ T _C = 100°C	12	Α	
I _{FM}	Diode Maximum Forward Current		92	Α	
P _D	Maximum Power Dissipation	@ T _C = 25°C	100	W	
	Maximum Power Dissipation	@ T _C = 100°C	40	W	
TJ	Operating Junction Temperature		-55 to +150	°C	
T _{stg}	Storage Temperature Range		-55 to +150	°C	
TL	Maximum Lead Temp. for Soldering Purposes, 1/8" from Case for 5 Seconds		300	°C	

Notes

(1) Repetitive rating : Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction-to-Case		1.2	°C/W
$R_{\theta JC}(DIODE)$	Thermal Resistance, Junction-to-Case		2.5	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Cha	racteristics					
BV _{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 250uA$	600			V
ΔB _{VCES} / ΔT _J	Temperature Coeff. of Breakdown Voltage	$V_{GE} = 0V$, $I_C = 1mA$		0.6		V/°C
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$			250	uA
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$			± 100	nA
On Char	racteristics					
V _{GE(th)}	G-E Threshold Voltage	$I_C = 12mA$, $V_{CE} = V_{GE}$	3.5	4.5	6.5	V
	Collector to Emitter	$I_C = 12A$, $V_{GE} = 15V$		2.1	2.6	V
V _{CE(sat)}	Saturation Voltage	$I_C = 23A$, $V_{GE} = 15V$		2.6		V
Dynami	c Characteristics					
C _{ies}	Input Capacitance	V 20V V 0V		720		pF
C _{oes}	Output Capacitance	$V_{CE} = 30V, V_{GE} = 0V,$ f = 1MHz		100		pF
C _{res}	Reverse Transfer Capacitance	I = IMIHZ		25		pF
Switchir	ng Characteristics					
t _{d(on)}	Turn-On Delay Time			17		ns
t _r	Rise Time			27		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		60	130	ns
t _f	Fall Time	$R_G = 23\Omega, V_{GE} = 15V,$		70	150	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 25°C		115		uJ
E _{off}	Turn-Off Switching Loss			135		uJ
E _{ts}	Total Switching Loss			250	400	uJ
t _{d(on)}	Turn-On Delay Time			23		ns
t _r	Rise Time			32		ns
t _{d(off)}	Turn-Off Delay Time	$V_{CC} = 300 \text{ V}, I_{C} = 12\text{A},$		100	200	ns
t _f	Fall Time	$R_G = 23\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 125^{\circ}C$		220	250	ns
E _{on}	Turn- On Switching Loss			205		uJ
E _{off}	Turn- Off Switching Loss			320		uJ
E _{ts}	Total Switching Loss			525	800	uJ
Q _g	Total Gate Charge	V = 200 V L = 124		49	80	nC
Q _{ge}	Gate-Emitter Charge	$V_{CE} = 300 \text{ V}, I_{C} = 12\text{A}, $ $V_{GE} = 15\text{V}$		11	17	nC
Q _{gc}	Gate-Collector Charge	VGE = 13 V		14	22	nC

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
V	Diode Forward Voltage	I _E = 12A	$T_C = 25^{\circ}C$		1.4	1.7	V
V_{FM}	Diode Forward Voltage	1 _F = 12A	T _C = 100°C		1.3] v
+	Diode Reverse Recovery Time		$T_C = 25^{\circ}C$		42	60	nc
t _{rr}	Diode Reverse Recovery Time		T _C = 100°C		80		ns
1	Diode Peak Reverse Recovery	I _F = 12A,	$T_C = 25^{\circ}C$		3.5	6.0	Α
¹rr	Current	di/dt = 200A/us	T _C = 100°C		5.6		
0	Diode Reverse Recovery Charge		$T_C = 25^{\circ}C$		80	180	nC
Q _{rr}			$T_C = 100^{\circ}C$		220		110

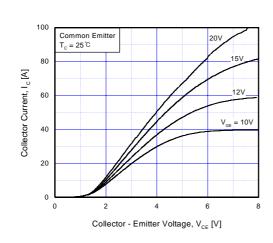


Fig 1. Typical Output Characteristics

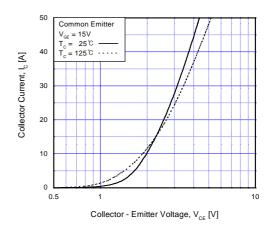


Fig 2. Typical Saturation Voltage Characteristics

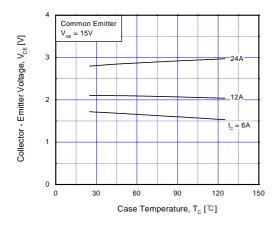


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

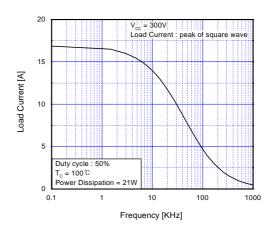


Fig 4. Load Current vs. Frequency

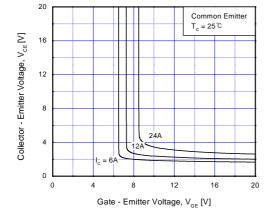


Fig 5. Saturation Voltage vs. V_{GE}

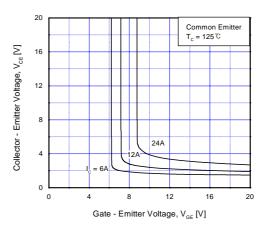
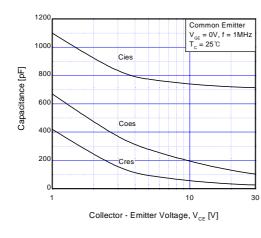


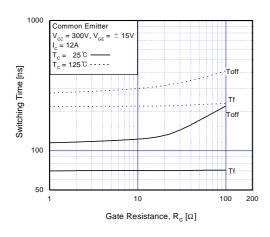
Fig 6. Saturation Voltage vs. V_{GE}



Common Emitter $V_{Cc} = 300V, V_{GE} = \pm 15V$ $I_{C} = 12A$ $T_{C} = 25 \, \text{C}$ $T_{C} = 125 \, \text{C}$ $T_{C} = 12$

Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs.
Gate Resistance



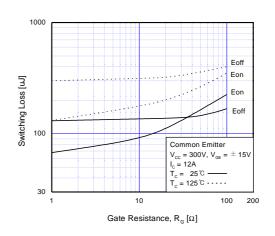
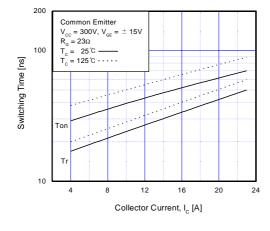


Fig 9. Turn-Off Characteristics vs.
Gate Resistance

Fig 10. Switching Loss vs. Gate Resistance



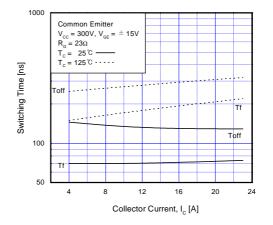
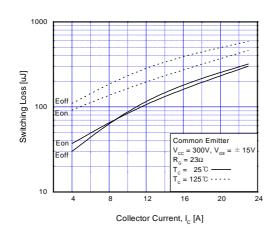


Fig 11. Turn-On Characteristics vs. Collector Current

Fig 12. Turn-Off Characteristics vs. Collector Current



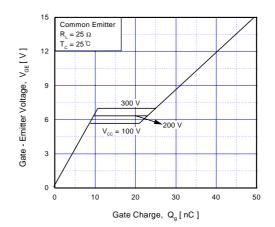
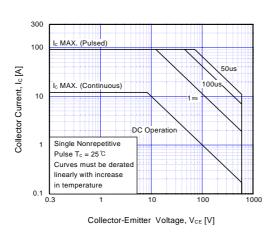


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



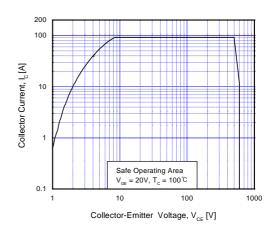


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

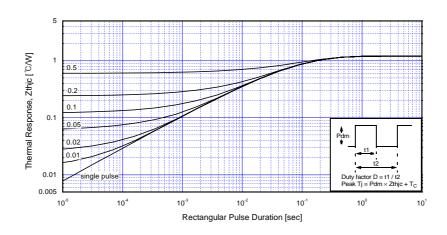
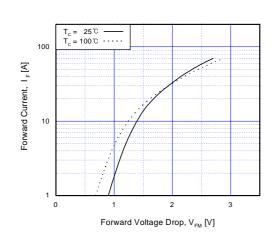


Fig 17. Transient Thermal Impedance of IGBT



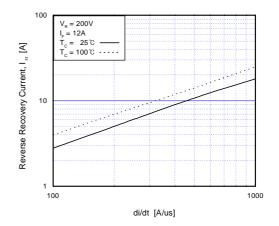
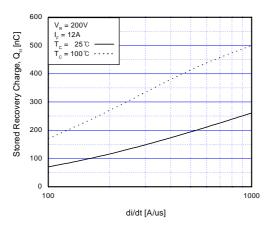


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



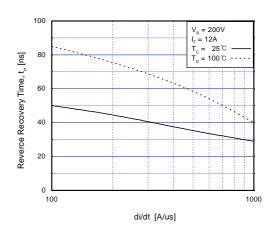


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time

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